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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/532,965	04/27/2005	Ja-Nam Ku	Q87567	9029
23373	7590	01/18/2008	EXAMINER	
SUGHRUE MION, PLLC 2100 PENNSYLVANIA AVENUE, N.W. SUITE 800 WASHINGTON, DC 20037			STONER, KILEY SHAWN	
ART UNIT		PAPER NUMBER		
1793				
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**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	10/532,965	KU ET AL.	
Examiner	Art Unit		
Kiley Stoner	1793		

**-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --**

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

## Status

1)  Responsive to communication(s) filed on 31 October 2007.

2a)  This action is **FINAL**.                            2b)  This action is non-final.

3)  Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

## **Disposition of Claims**

4)  Claim(s) 1,2 and 4-14 is/are pending in the application.

4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.

5)  Claim(s) \_\_\_\_\_ is/are allowed.

6)  Claim(s) 1,2 and 4-14 is/are rejected.

7)  Claim(s) \_\_\_\_\_ is/are objected to.

8)  Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

## Application Papers

9)  The specification is objected to by the Examiner.

10)  The drawing(s) filed on \_\_\_\_\_ is/are: a)  accepted or b)  objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)  The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)  Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
a)  All    b)  Some \* c)  None of:  
1.  Certified copies of the priority documents have been received.  
2.  Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
3.  Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

1)  Notice of References Cited (PTO-892) 4)  Interview Summary (PTO-413)  
2)  Notice of Draftsperson's Patent Drawing Review (PTO-948) Paper No(s)/Mail Date. \_\_\_\_\_  
3)  Information Disclosure Statement(s) (PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_  
5)  Notice of Informal Patent Application  
6)  Other: \_\_\_\_\_

## DETAILED ACTION

### ***Claim Rejections - 35 USC § 102***

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

**Claims 2, 9-12, and 14 are rejected under 35 U.S.C. 102(e) as being anticipated by Jairazbhoy et al. (US 2002/0000331 A1) (hereafter Jairazbhoy).**

Jairazbhoy teaches a compression bonding method comprising patterning bonding metal dots (16) on a metal substrate (80), disposing a second plurality of metal bonding film shapes (99) in a pattern on a bonded element (98), placing the bonding element above the bonding dots and applying heat to the substrate and pressure to the bonded element (figure 12B and paragraphs 36, 37, 43 and 49). The dots comprise aluminum (paragraph 37). In an alternate embodiment metal dots (62) are patterned on a metal substrate (80) which is bonded to a metal sheet (10). See figure 1B and paragraph 30. It is the examiner's position that since the distance between the components is controlled by metal bumps (16) element (98) would have to be subjected to a downward force in order to obtain the proper standoff between the components

being bonded. It should be further noted that gravity is pressing the element (98) downward.

***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

**Claims 1 and 5-8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Soga et al. (US 2006/0061974 A1) (hereafter Soga) as evidenced by Jochym.**

Jochym is solely used in this rejection to establish that one of ordinary skill in the art considers  $\text{Al}_2\text{O}_3$  a ceramic (note column 5, lines 22-25; and claim 18).

With respect to independent claim 1, Soga teaches a compression bonding method comprising disposing a plurality of metal bonding films (18) in a pattern directly on a substrate (13) made of a material selected from the group consisting of silicon and ceramic ( $\text{Al}_2\text{O}_3$  is considered a ceramic); and disposing a plate shaped bonded element (14) above the plurality of metal bonding film shapes and applying heat to the substrate and pressure to the bonded element, thereby bonding the bonded element to the substrate having the plurality of metal bonding film shapes, wherein the bonded element is plate shaped (Figure 7a and paragraphs 121 and 128-130). It should be noted that the pending claims are not limited to a substrate that only has one material layer.

Furthermore, Figure 3 of Soga teaches a heater (15) that is placed below the substrate, and a tool (7), which presses on the Si chip. Thus, Figure 3 meets the limitations of the claimed thermocompression bonding process. It is clearly obvious to one of ordinary skill in the art that the elements 8, 18 and 29 of Figure 7A could be assembled by the thermocompression bonding method depicted in Figure 3. Thus, the claim would have been obvious because a particular known technique was recognized as part of the ordinary capabilities of one skilled in the art.

With respect to claim 5, Soga teaches that the plurality of metal bonding film shapes are stripes or dots (Figure 7A).

With respect to claim 6, Soga teaches that the bonded element is glass or metal (14, W-Cu plating).

With respect to claim 7, Soga teaches that bonding occurs at a temperature below 350 C (paragraphs 2-5 and 78).

With respect to claim 8, Soga teaches that the bonded element contacts more than one of the plurality of metal bonding film shapes (Figure 7A).

**Claim 4 is rejected under 35 U.S.C. 103(a) as being unpatentable over Soga et al. (US 2006/0061974 A1) as applied to claim 1, and further in view of Jairazabhoi et al. (US 2002/0000331 A1).**

The teachings of Soga et al. are the same as relied upon in the rejection of claim 1. However, Soga et al. does not specifically disclose a metal bonding film made of a material selected from the group consisting of aluminum, magnesium, zinc, and

titanium. Jairazbhoy teaches a compression bonding method comprising patterning bonding metal dots (16) on a metal substrate (80), disposing a second bonding metal (99) on bonded element (98), placing the bonding element above the bonding dots and applying heat to the substrate and pressure to the bonded element (figure 12B and paragraphs 36, 37, 43 and 49). The dots comprise aluminum (paragraph 37). In an alternate embodiment metal dots (62) are patterned on a metal substrate (80) which is bonded to a metal sheet (10). See figure 1B and paragraph 30. Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to modify the invention of Soga et al. to include the metals disclosed by Jairazbhoy in order to control the ability of metals to clad together or plate onto each other and achieve desired relative reaction rates with known etchants (Jairazbhoy et al., [0037]).

**Claim 13 is rejected under 35 U.S.C. 103(a) as being unpatentable over Jairazbhoy et al. (US 2002/0000331 A1) as applied to claim 2, and further in view of Soga et al. (US 2006/0061974 A1).**

The teachings of Jairazbhoy et al. are the same as relied upon in the rejection of claim 2. Although it is known in the art that processing temperature will be dependent upon the solder material used, neither is the solder disclosed nor a processing temperature taught. Soga teaches a compression bonding method comprising patterning bonding metal dots (18, 21) on a substrate (29) (figure 7a and paragraphs 121 and 128-130) wherein bonding occurs at a temperature below 350 C (paragraphs 2-5 and 78). Thus, it would have been obvious to one of ordinary skill in the art at the

time of the invention to employ conventional low temperature solders to promote strong, reliable bonds without damaging electronic components.

### ***Response to Arguments***

Applicant's arguments filed 10/31/07 have been fully considered but they are not persuasive.

Jochym clearly establishes that one of ordinary skill in the art would consider  $\text{Al}_2\text{O}_3$  a ceramic. In addition, in view of the broadest reasonable interpretation it is the examiner's position that element 99 of Jairazbhoy is disposed in a pattern on bonding element 98. The examiner reminds the applicant that during patent examination, the pending claims must be "given the broadest reasonable interpretation." Applicant always has the opportunity to amend the claims during prosecution, and broad interpretation by the examiner reduces the possibility that the claim, once issued, will be interpreted more broadly than is justified. In re Prater, 415 F.2d 1393, 1404-05, 162 USPQ 541, 550-51 (CCPA 1969).

### ***Conclusion***

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Kiley Stoner whose telephone number is 571-272-1183. The examiner can normally be reached Monday-Thursday (9:30 a.m. to 8:00 p.m.).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Jonathan Johnson can be reached on 571-272-1177. The fax phone

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number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

*Kiley Stoner* 11/14/08

Kiley Stoner

Primary Examiner A.U. 1793